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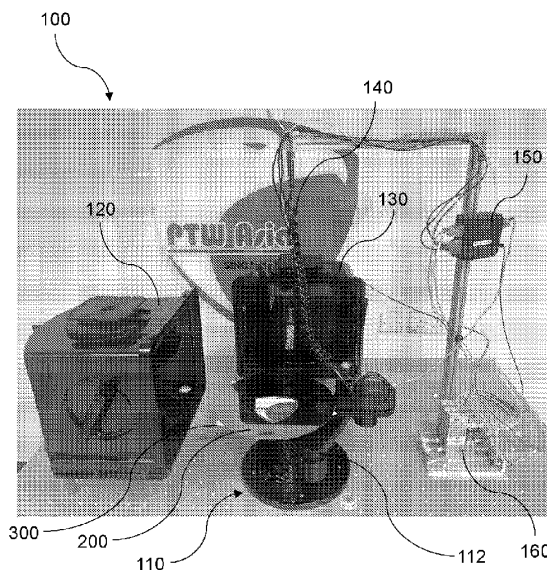


Figure 1B

(57) Abstract: The present disclosure generally relates to a system (100) and method (400) for contactless handling of a semiconductor wafer (200). The system (100) comprises: a wafer table (300) for supporting the semiconductor wafer (200) without physical contact between them, the wafer table (300) comprising fluidic outlets for discharging gas; pneumatic lines (140) for communicating gas to the fluidic outlets; and a pneumatic controller (150) for controlling gas communication in the pneumatic lines (140) to thereby selectively discharge gas from the fluidic outlets. A first set of the fluidic outlets discharges gas therefrom such that the discharged gas contactlessly supports the semiconductor wafer (200) relative to the wafer table (300). A second set of the fluidic outlets discharge gas therefrom such that the discharged gas rotates the semiconductor wafer (200) while the semiconductor wafer (200) is being contactlessly supported by the wafer table (300). The pneumatic controller (150) controls gas discharge from the first and second sets of fluidic outlets to thereby

[Continued on next page]

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control support and rotation of the semiconductor wafer (200).